

### 3.2 x 2.7 x 0.8mm Red & Pure Green & Blue Chip LED

### OSTB3227C1C-A

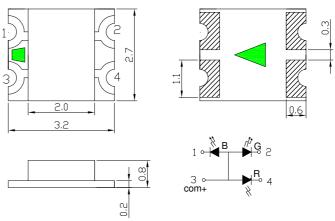
#### **■Features**

- Full-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline
   (LxWxT) of 3.2mm x 2.7mm x 0.8mm
- Compatible to IR reflow soldering.

## Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

#### **Outline Dimension**

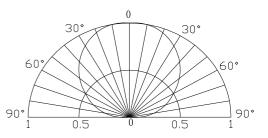


Notes: 1. All dimensions are in millimeters; 2. Tolerance is  $\pm$  0.10 mm unless otherwise noted.

### ■Absolute Maximum Rating

	0	`			
Item	Symbo	Val	Unit		
пеш	1	HR	PG/BL		
DC Forward Current	$I_F$	30	30	mA	
Pulse Forward Current*	$I_{FP}$	70	100	mA	
Reverse Voltage	$V_R$	5	5	V	
Power Dissipation	$P_{\mathrm{D}}$	78	108	mW	
Operating Temperature	Topr	-25 ~	$^{\circ}\! C$		
Storage Temperature	Tstg	-35~	$^{\circ}\!\mathbb{C}$		
Lead Soldering Temperature	Tsol	260°C	-		

### **■**Directivity



### **■**Electrical -Optical Characteristics

### (Ta=25°C)

(Ta=25°C)

			$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)		2θ1/2(deg)				
Part Number Color	Color		Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Typ.	
			I <sub>F</sub> =20mA		V <sub>R</sub> =5V	I <sub>F</sub> =20mA								
OSTB3227C1C-A	Blue	BL		2.8	3.1	3.6	10	-	90	-	465	470	475	120
	Pure Green	PG		2.8	3.1	3.6	10	-	300	-	520	525	530	120
	Red	HR		1.8	2.1	2.6	10	-	100	-	620	625	630	120

<sup>\*1</sup> Tolerance of measurements of dominant wavelength is ±1nm

# **LED & Application Technologies**











http://www.optosupply.com VER A.3.1

<sup>\*</sup>Pulse width Max 0.1ms, Duty ratio max 1/10

<sup>\*2</sup> Tolerance of measurements of luminous intensity is  $\pm 15\%$ 

<sup>\*3</sup> Tolerance of measurements of forward voltage is  $\pm 0.1 \text{V}$ 

#### 3.2 x 2.7 x 0.8mm Red & Pure Green & Blue Chip LED

#### OSTB3227C1C-A

#### **■ Cautions:**

- 1. After open the package, the LED's floor life is 1 year under 30° C or less and 60%RH or less (MSL:2).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
- 8. OPTOSUPPLY will not do 4M change without advance consultation.





